



Thank you for attending the 64th ECTC!

I would like to thank all authors, presenters, program committee! members, exhibitors, sponsors, volunteers and all attendees for making the 64th ECTC such a well-attended success.

Here are some conference statistics:

- 1,170 attendees, the highest attendance ever in Orlando
- Attendees came from 33 different countries - another all-time high!
- 369 technical papers, presented in 36 oral and five interactive presentation sessions, including a student poster session
- Nine sessions focused on 3D/TSV, including several of the best-attended sessions of the conference
- 18 professional development courses attended by more than 400 participants - both numbers are record highs as well
- 101 Technology Corner exhibitors - also a new record! (more than 90 of our exhibitors already re-signed for next year, which tells you much about the success)

In addition to the regular daytime sessions and courses, we offered two special sessions on Tuesday and three evening seminars that were all very well attended:

- **ECTC Special Session**
 - Chaired by Karlheinz Bock of Fraunhofer EMFT on technology and application trends in the field of flexible electronics
- **ECTC Panel Session**
 - Co-chaired by Jie Xue of Cisco Systems and Ricky Lee of Hong Kong University of Science & Technology on emerging technologies and market trends of silicon photonics
- **ECTC Plenary Session**
 - Chaired by Nancy Stoffel of GE Global Research on the contribution and influence of packaging on system integration and performance
- **CPMT Seminar**
 - Co-chaired by Kishio Yokouchi of Fujitsu Interconnect Technologies Ltd. and Venky Sundaram of the Georgia Institute of Technology covering the latest advances in organic interposers
- **Electronic Components and RF Special Session**
 - Co-chaired by Manos Tentzeris of the Georgia Institute of Technology and Craig Gaw of Freescale on wireless power transfer systems

Finally, the ECTC Keynote Speaker, Dr. Peter Bocko, CTO of Corning Glass Technologies, provided a very interesting and holistic view of the use and significance of glass in both a

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scientific as well as artistic role.

I would like to thank our corporate sponsors - particularly our Gala sponsors: Nanium, Amkor, DOW Electronic Materials, SPTS, AMAT, and Micron, as well as our Luncheon, Program, and Special sponsors: Amkor, ASE, Corning, GLOBALFOUNDRIES, HD Microsystems, IBM, Intel, Microsoft, NCAP, SPIL and TOK. Photos taken at the conference [are posted](#) on Flickr.

Next year's conference will be held 26-29 May 2015, at the Sheraton Hotel & Marina in San Diego, California, USA.

I think you will find it to be an amazing venue, and I hope to see you there.

Best,



Wolfgang Sauter
General Chair, 64th Electronic Components and Technology Conference
IBM Corporation

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